

National Aeronautics and Space Administration



Update on Wide Bandgap (WBG) Device Radiation Hardness Assurance

Jean-Marie Lauenstein, Jason Osheroff, Ted Wilcox, Megan Casey, and Emmanual Hernandez – NASA GSFC Anthony Phan, Hak Kim, and Alyson Topper – SSAI

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Abbreviations and Acronyms



| Acronym | Definition |
|-------------------|--|
| BJT | Bipolar Junction Transistor |
| BV _{DSS} | Drain-Source Breakdown Voltage |
| DDD | Displacement Damage Dose |
| ETW | Electronics Technology Workshop |
| GaN | Gallium Nitride |
| GCR | Galactic Cosmic Ray |
| HEMT | High Electron Mobility Transistor |
| I _D | Drain Current |
| IEEE | Institute of Electrical and Electronics Engineers |
| JBS | Junction Barrier Schottky |
| JFET | Junction Field Effect Transistor |
| LBNL | Lawrence Berkeley National Laboratory |
| LET | Linear Energy Transfer |
| MOSFET | Metal Oxide Semiconductor Field Effect Transistor |

| Acronym | Definition |
|-----------------|---|
| NSREC | Nuclear and Space Radiation Effects Conference |
| REAG | Radiation Effects & Analysis Group |
| RF | Radio Frequency |
| RHA | Radiation Hardness Assurance |
| SEB | Single-Event Burnout |
| SEE | Single-Event Effect |
| Si | Silicon |
| SiC | Silicon Carbide |
| SMD | Science Mission Directorate |
| SOA | State Of the Art; Safe Operating Area |
| STMD | Space Technology Mission Directorate |
| SWAP | Size, Weight, And Power |
| TAMU | Texas A&M University cyclotron facility |
| TCAD | Technology Computer-Aided Design |
| VDMOS | Vertical Double-diffused MOSFET |
| V _{DS} | Drain-Source Voltage |

Outline



- Enhancement-mode power GaN activities
 - Heavy-ion radiation test updates
 - Upcoming test plans
- **RF GaN activities**
 - Radiation test method evaluation plans
 - GSFC test capability development
- SiC power device research activity
 - SiC single-event effect failure mechanisms

NASA "Pulls" for WBG power technology include science instrument and avionic & space power applications





images: NASA

Single-Event Effect (SEE) Test Results: Normally-Off GaN HEMT



• SSDI SGF15E100 1000-V, 15 A:



- Cascoded design to achieve normally-off operation
- MIL-PRF-19500 S-Level screening available

SEE Test Results: Normally-Off GaN HEMT



- SSDI SGF15E100 1000-V, 15 A:
- SEB at 350 V_{DS} for LET(Si) = 42 MeV-cm²/mg





SEE Test Results: Normally-Off GaN HEMT



- SSDI SGF15E100 1000-V, 15 A:
- SEB at 350 V_{DS} for LET(Si) = 42 MeV-cm²/mg
- Non-catastrophic degradation of I_D
 - At higher LET (Ag), becomes substantial (mA levels) near threshold V_{DS} for SEB
 - With lighter Cu ions, can reach standard test fluences to identify low cross-section SEB event





Planned eGaN Activities



- Joint heavy-ion SEE test with a GaN manufacturer:
 - Evaluate our new power device test board featuring low parasitics
 - Lower risk of systematic influences on test data
 - Validate manufacturer test data
- Combined-effects testing for displacement damage dose (DDD) influence on SEE
 - STMD Kilopower Project in partnership with GaN supplier



Fission nuclear power system for planetary surface habitation. Image: NASA

RF GaN Test Plans and Capability



Plan:

- RF mode vs. static mode for catastrophic SEE assessment
 - Increase the body of data and devices evaluated to support test method standards

GSFC REAG Infrastructure Development:

- RF test setup:
 - Currently for high-wattage S & C bands;
 - Ability to expand up to Ka band
 - Power amplifier uses GaN HEMT technology!



SiC Power Device Research Activity



- NASA STMD Early-Stage Innovation (ESI) grants funded efforts to increase our understanding of the heavy-ion radiation effects in SiC power devices
 - Publications:
 - [1] R. A. Johnson, et al., "Unifying Concepts for Ion-Induced Leakage Current Degradation in Silicon Carbide Schottky Power Diodes," IEEE Trans Nucl Sci, vol. 67, pp. 135-139, 2020.
 - [2] D. R. Ball, *et al.*, "Ion-Induced Energy Pulse Mechanism for Single-Event Burnout in High-Voltage SiC Power MOSFETs and Junction Barrier Schottky Diodes," *IEEE Trans Nucl Sci*, vol. 67, pp. 22-28, 2020.
 - [3] R. A. Austin, *et al.*, "Inclusion of Radiation Environment Variability for Reliability Estimates for SiC Power MOSFETs," *IEEE Trans Nucl Sci*, vol. 67, pp. 353-357, 2020.
 - [4] J. A. McPherson, *et al.*, "Mechanisms of Heavy Ion Induced Single Event Burnout in 4H-SiC Power MOSFETs," presented at ICSCRM, Kyoto, Japan, 2019.
 - [5] J. A. McPherson, *et al.*, "Heavy Ion Transport Modeling for Single-Event Burnout in SiC-Based Power Devices," *IEEE Trans Nucl Sci,* vol. 66, pp. 474-481, 2019.
 - [6] R. A. Johnson, *et al.*, "Enhanced Charge Collection in SiC Power MOSFETs Demonstrated by Pulse-Laser Two-Photon Absorption SEE Experiments," *IEEE Trans Nucl Sci,* vol. 66, pp. 1694-1701, 2019.
 - [7] D. R. Ball, et al., "Estimating Terrestrial Neutron-Induced SEB Cross Sections and FIT Rates for High-Voltage SiC Power MOSFETs," IEEE Trans Nucl Sci, vol. 66, pp. 337-343, 2019.
 - [8] A. F. Witulski, et al., "Single-Event Burnout Mechanisms in SiC Power MOSFETs," IEEE Trans Nucl Sci, vol. 65, pp. 1951-1955, 2018.
 - [9] A. F. Witulski, *et al.*, "Single-Event Burnout of SiC Junction Barrier Schottky Diode High-Voltage Power Devices," *IEEE Trans Nucl Sci*, vol. 65, pp. 256-261, 2018.
 - [10] A. Javanainen, et al., "Molecular Dynamics Simulations of Heavy Ion Induced Defects in SiC Schottky Diodes," IEEE Trans Dev Mater Rel, vol. 18, pp. 481-483, 2018.
 - [11] K. F. Galloway, et al., "Failure Estimates for SiC Power MOSFETs in Space Electronics," Aerospace, vol. 5, p. 67, 2018.
 - Look for more presentations at IEEE NSREC 2020!

Highlights of SiC SEB Mechanism Research





 Laser tests suggest MOSFET bipolar structure can turn on despite poor gain

- Suggested SEB mechanism similar to Si



Highlights of SiC SEB Mechanism Research





D. R. Ball, et al., IEEE TNS 2020

BUT:

- 1200-V SiC MOSFET and JBS diode have similar SEE thresholds
- SEB in MOSFET despite protective-mode (voltage quenching) test circuit
- Behavior is similar for short time (<100 ps) after ion strike

- TCAD: 500 V_{DS} with LET(SiC) = 10 MeV-cm²/mg



Highlights of SiC SEB Mechanism Research





- Ion strike redistributes electric field in epitaxial region
- Field peaks at back epi-n⁺ drain interface for both MOSFET and diode
- Power density extremely high over epi region, with extremely fast generation
- Per T. Shoji, et al., heat generation density 100x faster in SiC than in Si

Conclusions



- WBG power devices enable game-changing power systems
 - Spacecraft transport
 - Lunar and planetary surface power
 - Electric aircraft
 - Science instruments
- Advancement of space radiation risk identification and mitigation will assure onorbit reliability of systems built from these new technologies
- NASA will continue to mature radiation hardness assurance for WBG technology
 - In-house efforts
 - Leveraged partnerships and collaborations
 - Contract and grant initiatives

